

SEMiX151GAL12Vs



SEMiX[®] 1s

SEMiX151GAL12Vs

Features

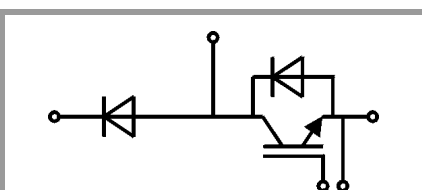
- Homogeneous Si
- $V_{CE(sat)}$ with positive temperature coefficient
- High short circuit capability
- UL recognised file no. E63532

Typical Applications*

- AC inverter drives
- UPS
- Electronic Welding

Remarks

- Case temperature limited to $T_C=125^\circ\text{C}$ max.
- Product reliability results are valid for $T_j=150^\circ\text{C}$



GAL

Absolute Maximum Ratings				
Symbol	Conditions		Values	Unit
IGBT				
V_{CES}	$T_j = 25^\circ\text{C}$		1200	V
I_C	$T_j = 175^\circ\text{C}$	$T_c = 25^\circ\text{C}$	231	A
		$T_c = 80^\circ\text{C}$	176	A
I_{Cnom}			150	A
I_{CRM}	$I_{CRM} = 3 \times I_{Cnom}$		450	A
V_{GES}			-20 ... 20	V
t_{psc}	$V_{CC} = 720\text{ V}$	$T_j = 125^\circ\text{C}$	10	μs
	$V_{GE} \leq 15\text{ V}$			
	$V_{CES} \leq 1200\text{ V}$			
T_j			-40 ... 175	$^\circ\text{C}$
Inverse diode				
I_F	$T_j = 175^\circ\text{C}$	$T_c = 25^\circ\text{C}$	189	A
		$T_c = 80^\circ\text{C}$	141	A
I_{Fnom}			150	A
I_{FRM}	$I_{FRM} = 3 \times I_{Fnom}$		450	A
I_{FSM}	$t_p = 10\text{ ms, sin } 180^\circ, T_j = 25^\circ\text{C}$		900	A
T_j			-40 ... 175	$^\circ\text{C}$
Freewheeling diode				
I_F	$T_j = 175^\circ\text{C}$	$T_c = 25^\circ\text{C}$	189	A
		$T_c = 80^\circ\text{C}$	141	A
I_{Fnom}			150	A
I_{FRM}	$I_{FRM} = 3 \times I_{Fnom}$		450	A
I_{FSM}	$t_p = 10\text{ ms, sin } 180^\circ, T_j = 25^\circ\text{C}$		900	A
T_j			-40 ... 175	$^\circ\text{C}$
Module				
$I_{t(RMS)}$	$T_{terminal} = 80^\circ\text{C}$		600	A
T_{stg}			-40 ... 125	$^\circ\text{C}$
V_{isol}	AC sinus 50Hz, $t = 1\text{ min}$		4000	V

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
IGBT						
$V_{CE(sat)}$	$I_C = 150\text{ A}$ $V_{GE} = 15\text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$	1.75	2.2		V
		$T_j = 150^\circ\text{C}$		2.2	2.5	V
V_{CE0}		$T_j = 25^\circ\text{C}$	0.94		1.04	V
		$T_j = 150^\circ\text{C}$	0.88		0.98	V
r_{CE}	$V_{GE} = 15\text{ V}$	$T_j = 25^\circ\text{C}$	5.4		7.7	$\text{m}\Omega$
		$T_j = 150^\circ\text{C}$		8.8	10.1	$\text{m}\Omega$
$V_{GE(th)}$	$V_{GE} = V_{CE}, I_C = 6\text{ mA}$		5.5	6	6.5	V
I_{CES}	$V_{GE} = 0\text{ V}$ $V_{CE} = 1200\text{ V}$	$T_j = 25^\circ\text{C}$		0.1	0.3	mA
		$T_j = 150^\circ\text{C}$				mA
C_{ies}	$V_{CE} = 25\text{ V}$ $V_{GE} = 0\text{ V}$	$f = 1\text{ MHz}$		9.0		nF
C_{oes}		$f = 1\text{ MHz}$		0.89		nF
C_{res}		$f = 1\text{ MHz}$		0.88		nF
Q_G	$V_{GE} = -8\text{ V...} + 15\text{ V}$			1650		nC
R_{Gint}	$T_j = 25^\circ\text{C}$			5.00		Ω

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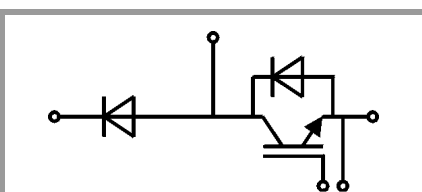
Typical Applications*

- AC inverter drives
- UPS
- Electronic Welding

Remarks

- Case temperature limited to $T_C=125^\circ\text{C}$ max.
- Product reliability results are valid for $T_j=150^\circ\text{C}$

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
$t_{d(on)}$	$V_{CC} = 600\text{ V}$	$T_j = 150^\circ\text{C}$		319		ns
t_r	$I_C = 150\text{ A}$	$T_j = 150^\circ\text{C}$		46		ns
E_{on}	$V_{GE} = \pm 15\text{ V}$	$T_j = 150^\circ\text{C}$		19.4		mJ
$t_{d(off)}$	$R_{G\ on} = 1\ \Omega$	$T_j = 150^\circ\text{C}$		482		ns
t_f	$R_{G\ off} = 1\ \Omega$	$T_j = 150^\circ\text{C}$		68		ns
E_{off}	$di/dt_{on} = 4600\text{ A}/\mu\text{s}$ $di/dt_{off} = 1700\text{ A}/\mu\text{s}$ $du/dt_{off} = 6700\text{ V}/\mu\text{s}$	$T_j = 150^\circ\text{C}$		17.1		mJ
$R_{th(j-c)}$	per IGBT				0.19	K/W
Inverse diode						
$V_F = V_{EC}$	$I_F = 150\text{ A}$	$T_j = 25^\circ\text{C}$		2.1	2.46	V
	$V_{GE} = 0\text{ V}$ chip	$T_j = 150^\circ\text{C}$		2.1	2.4	V
V_{F0}		$T_j = 25^\circ\text{C}$	1.1	1.3	1.5	V
		$T_j = 150^\circ\text{C}$	0.7	0.9	1.1	V
r_F		$T_j = 25^\circ\text{C}$	4.3	5.6	6.4	m Ω
		$T_j = 150^\circ\text{C}$	7.0	7.8	8.5	m Ω
I_{RRM}	$I_F = 150\text{ A}$	$T_j = 150^\circ\text{C}$		175		A
Q_{rr}	$di/dt_{off} = 4400\text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$		27.5		μC
E_{rr}	$V_{GE} = -15\text{ V}$ $V_{CC} = 600\text{ V}$	$T_j = 150^\circ\text{C}$		11.5		mJ
$R_{th(j-c)}$	per diode				0.31	K/W
Freewheeling diode						
$V_F = V_{EC}$	$I_F = 150\text{ A}$	$T_j = 25^\circ\text{C}$		2.1	2.46	V
	$V_{GE} = 0\text{ V}$ chip	$T_j = 150^\circ\text{C}$		2.1	2.4	V
V_{F0}		$T_j = 25^\circ\text{C}$	1.1	1.3	1.5	V
		$T_j = 150^\circ\text{C}$	0.7	0.9	1.1	V
r_F		$T_j = 25^\circ\text{C}$	4.3	5.6	6.4	m Ω
		$T_j = 150^\circ\text{C}$	7.0	7.8	8.5	m Ω
I_{RRM}	$I_F = 150\text{ A}$	$T_j = 150^\circ\text{C}$		175		A
Q_{rr}	$di/dt_{off} = 4400\text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$		27.5		μC
E_{rr}	$V_{GE} = -15\text{ V}$ $V_{CC} = 600\text{ V}$	$T_j = 150^\circ\text{C}$		11.5		mJ
$R_{th(j-c)}$	per diode				0.31	K/W
Module						
L_{CE}				16		nH
R_{CC+EE}	res., terminal-chip	$T_C = 25^\circ\text{C}$		0.7		m Ω
		$T_C = 125^\circ\text{C}$		1		m Ω
$R_{th(c-s)}$	per module			0.075		K/W
M_s	to heat sink (M5)		3		5	Nm
M_t		to terminals (M6)	2.5		5	Nm
						Nm
w					145	g
Temperatur Sensor						
R_{100}	$T_C = 100^\circ\text{C}$ ($R_{25} = 5\text{ k}\Omega$)			$493 \pm 5\%$		Ω
$B_{100/125}$	$R(T) = R_{100} \exp[B_{100/125}(1/T - 1/T_{100})]$; T[K];			$3550 \pm 2\%$		K



GAL

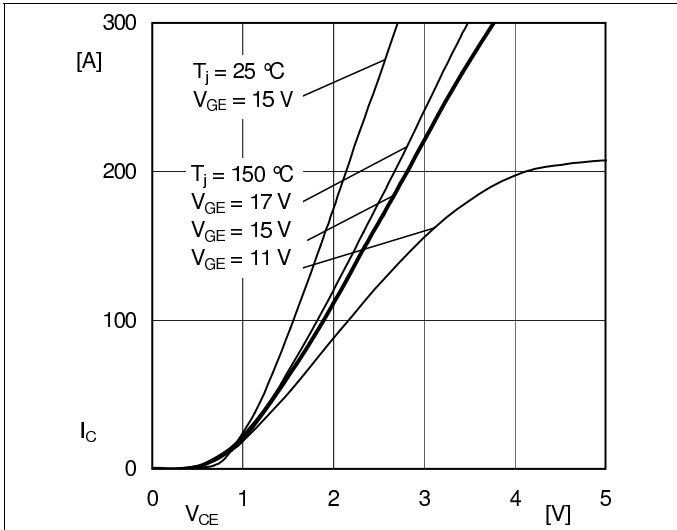


Fig. 1: Typ. output characteristic, inclusive R_{CC+EE}

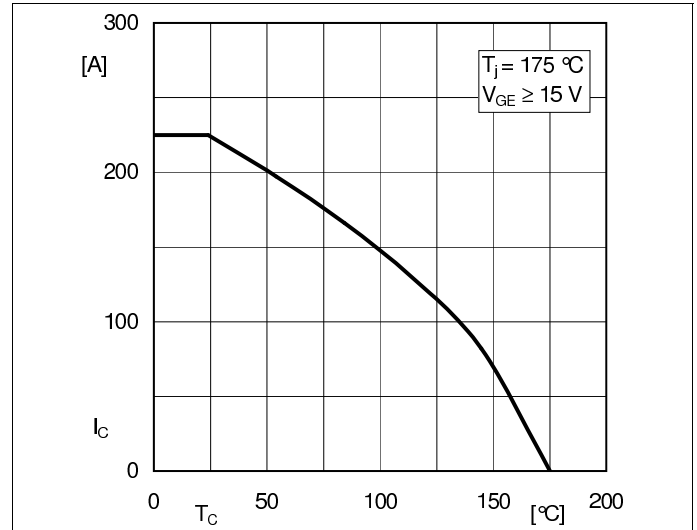


Fig. 2: Rated current vs. temperature $I_C = f(T_C)$

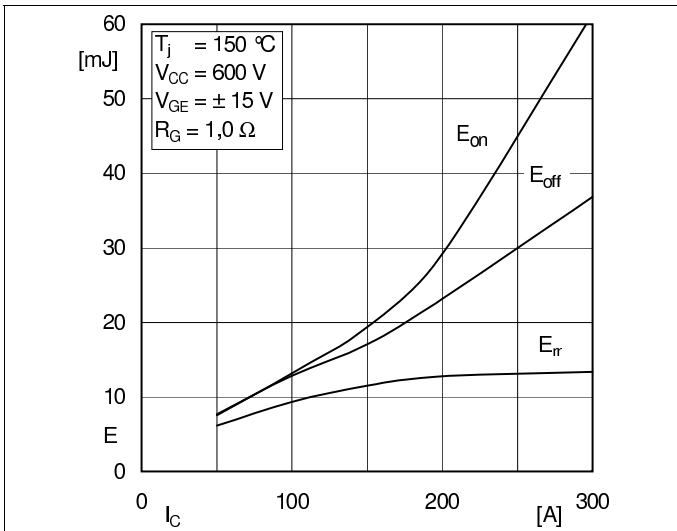


Fig. 3: Typ. turn-on /-off energy = $f(I_C)$

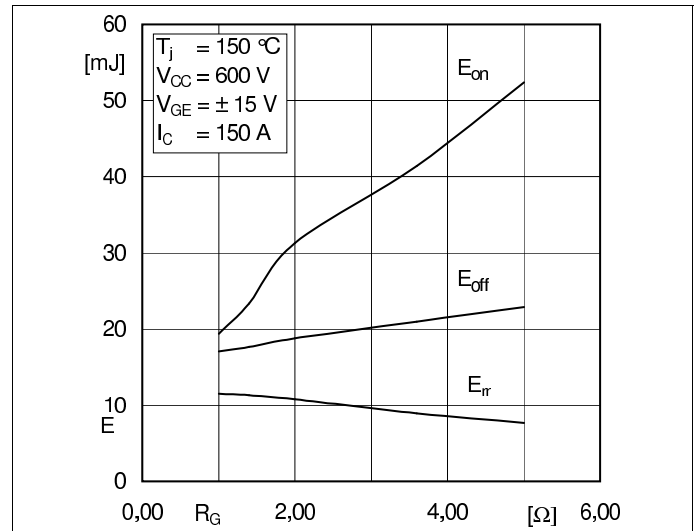


Fig. 4: Typ. turn-on /-off energy = $f(R_G)$

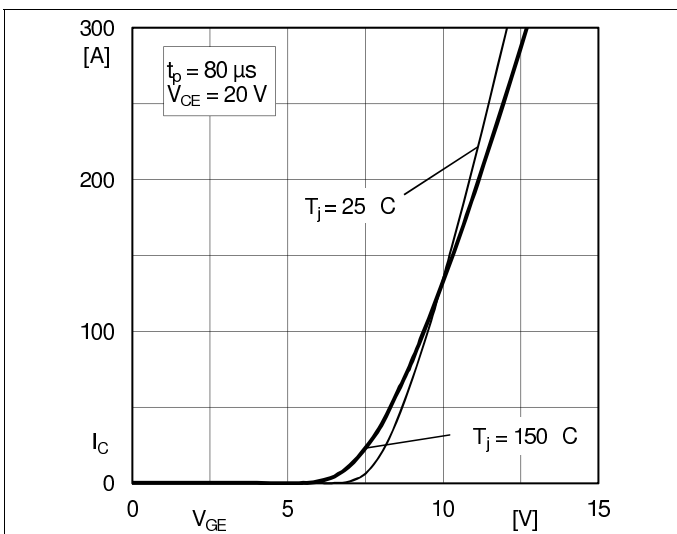


Fig. 5: Typ. transfer characteristic

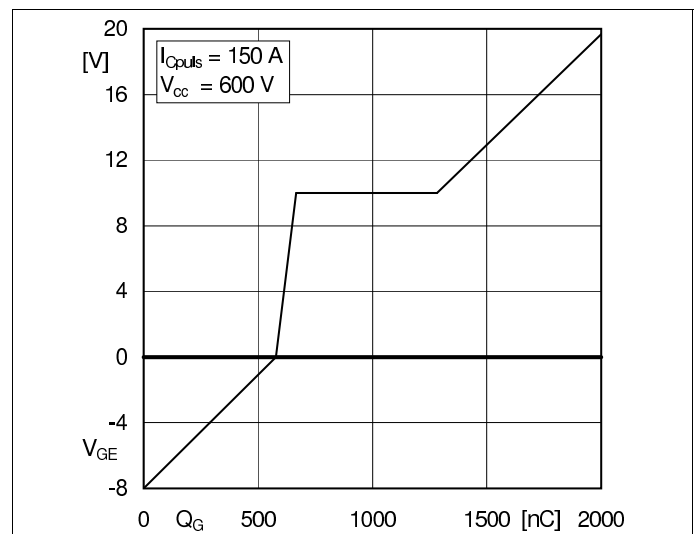
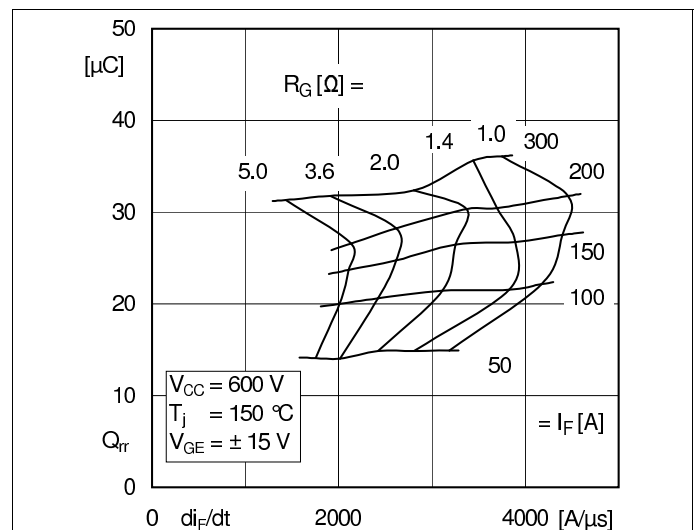
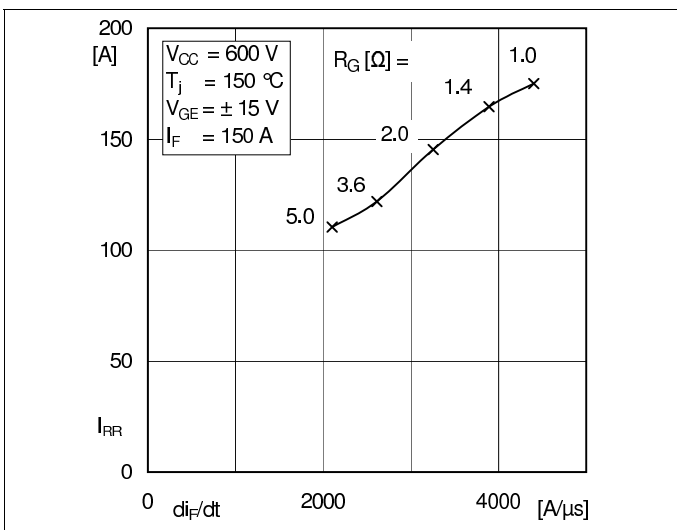
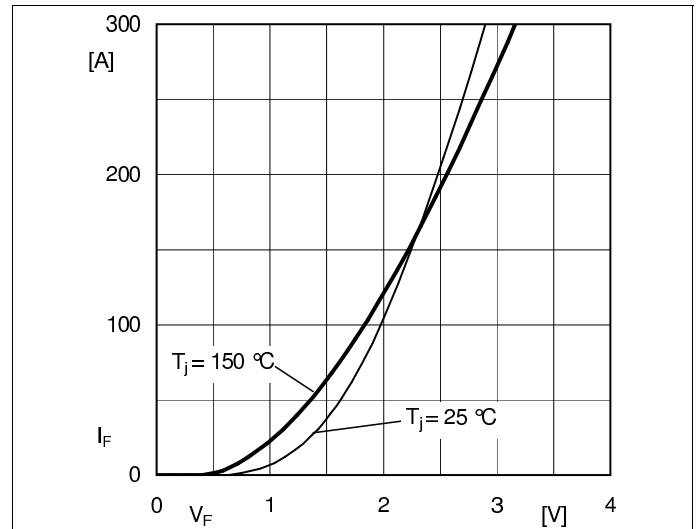
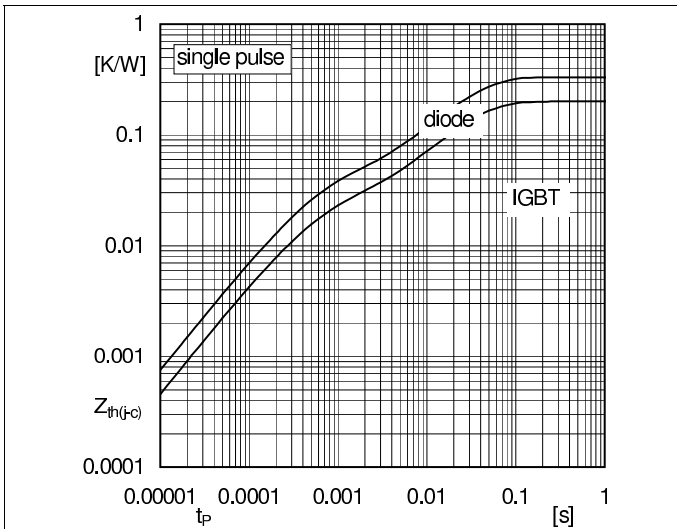
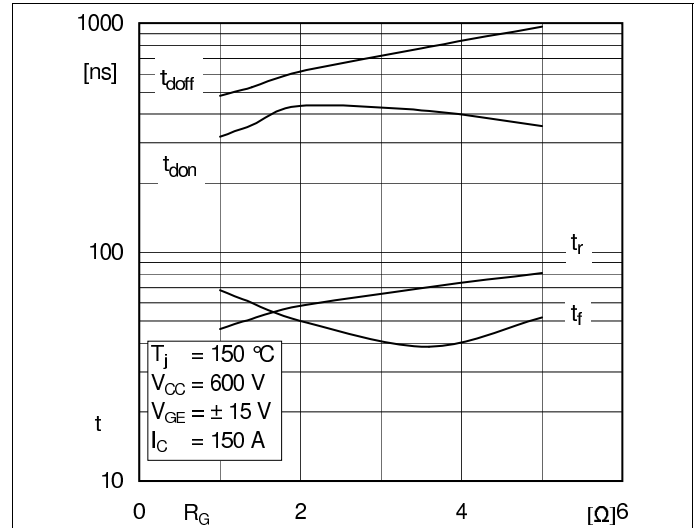
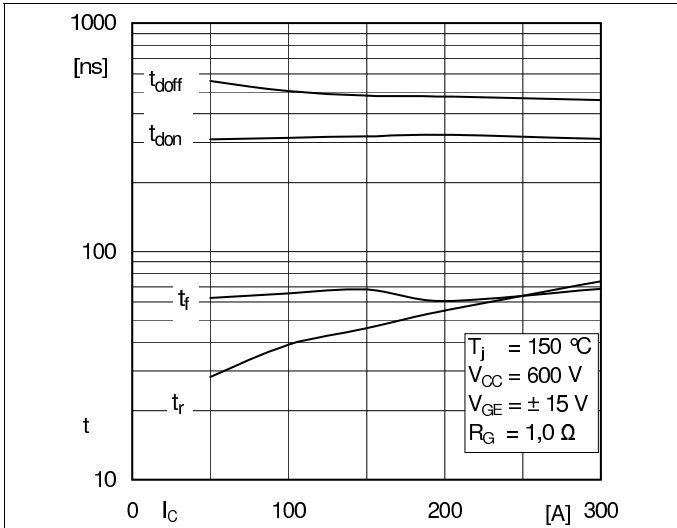


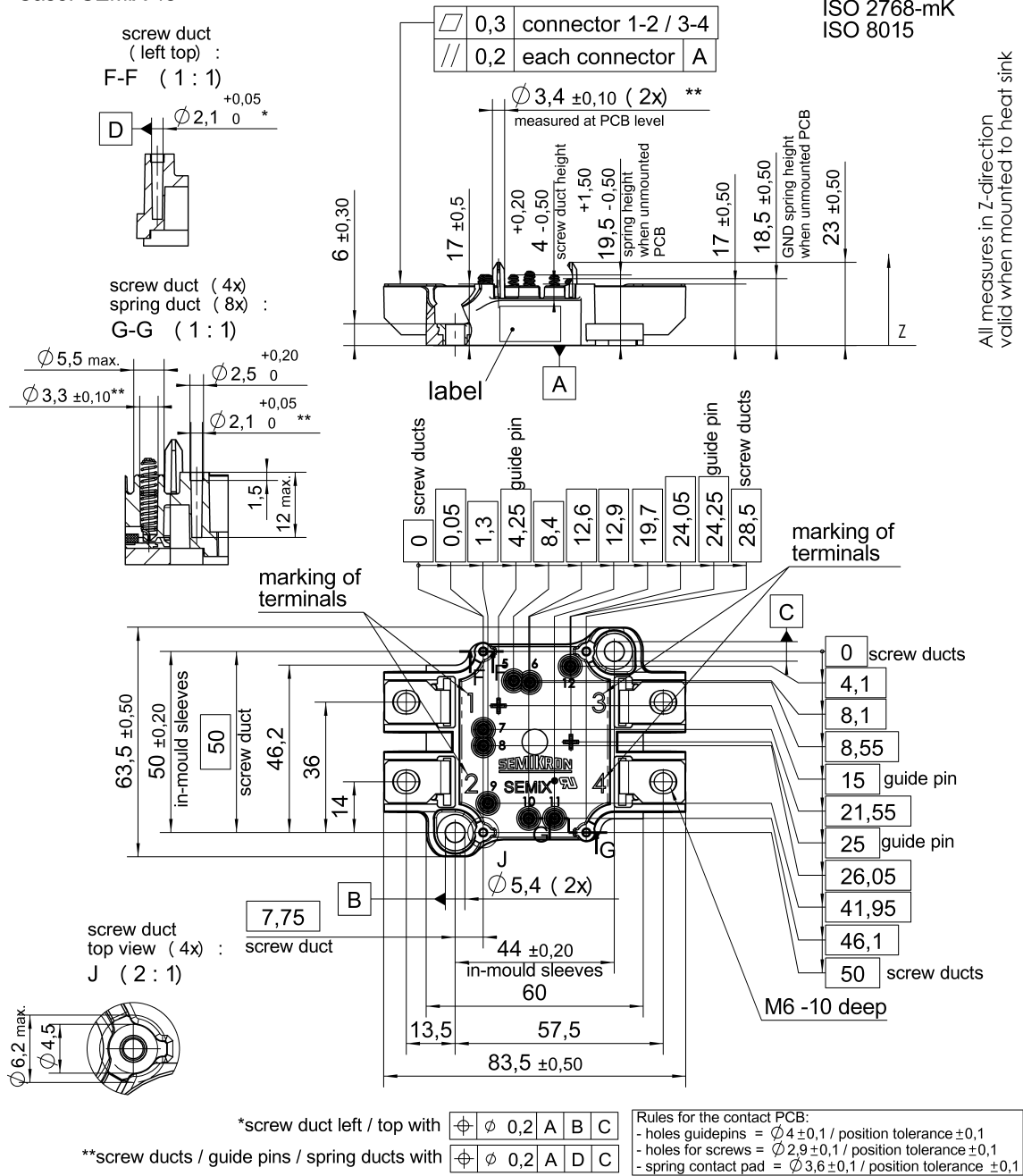
Fig. 6: Typ. gate charge characteristic



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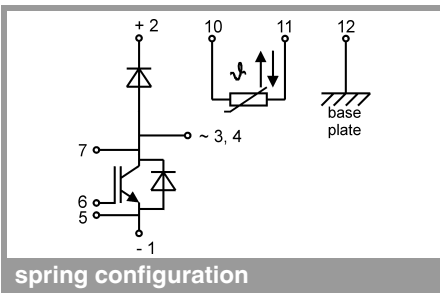
Case: SEMiX 1s

general tolerance:
ISO 2768-mK
ISO 8015



All measures in Z-direction valid when mounted to heat sink

SEMiX 1s



This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our staff.